

Sensors and Materials

Special Issue on Advanced Sensors Materials and Processes

Call for Papers

There are many applications where sensors, such as strength, distance, height, and pressure sensors, are used daily. Sensors are also heavily used in aerospace, intelligent manufacturing, and IoT. This special issue focuses on the advanced materials and processing technologies of sensors used in everyday life, manufacturing, and IoT applications, including materials, systems, design, and manufacturing techniques. The materials used can be carbon, metals, ceramics, polymers, and related composite materials. We also welcome papers on sensor applications of biomolecular materials, microorganisms, and various organic and inorganic materials.

Scope:

Sensor design	Sensors in life
Sensor materials	Sensors in manufacturing
Sensor applications	Sensors in IoT
Sensor fabrication	Sensors in systems
Intelligent sensors	Sensors in biomedicine

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If you have any questions, please feel free to contact the editorial staff at the address below.

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